



MGXS6 series Reliability test results

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OS DESIGN DEPT.

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| No. | Test Item | Testing conditions | Conditions of acceptability | Number of samples | Number of failures |
|-----|---|---|---|-------------------|--------------------|
| 1 | Heat cycle test | (1) $-40^{\circ}\text{C} \sim 125^{\circ}\text{C}$ 30minutes each (2) 800cycles | (1)No degradation of electric characteristics after test. (2)No crack at solder joint. | 5 | 0 |
| 2 | High temperature/ High humidity bias test | (1) $T_a=85^{\circ}\text{C}$, RH=85% (2) Input Max.Voltege (3) Load 0% (4) 1000hours | (1)No degradation of electric characteristics after test. | 5 | 0 |
| 3 | Vibration test | (1) $f=10\sim 55\text{Hz}$, 98.0m/s^2 (10G) (2) 3minutes period (3) 60minutes each X, Y and Z axis | (1)No degradation of electric characteristics after test. (2)No crack at solder joint. (3)No mechanical damage of appearance. | 6 | 0 |
| 4 | Impact test | (1) 490.3m/s^2 (50G), 11ms (2) Once each X, Y and Z axis | (1)No degradation of electric characteristics after test. (2)No crack at solder joint. (3)No thermal damage of appearance. | 3 | 0 |
| 5 | Soldering heat test | (1) Soldering iron $340\sim 360^{\circ}\text{C}$, 7.5 seconds (2) Mounting board : $t=1.6\text{mm}$ / FR4 | (1)No crack at solder joint. (2)No marked damage of appearance. | 1 | 0 |
| 6 | Pin solder ability test | (1) Pre-process Step1 Humidifying processing (100°C , 100%, 1H) Step2 Dip into flux (2) Dip soldering $230\sim 240^{\circ}\text{C}$, 2sec | (1)Over 95% of dipped part is covered with solder. | 3 | 0 |
| 7 | Pin strength test | (1) Weight : 1kg (2) Bending angle : 90 deg., total 180 deg. (3) 1 cycle | (1)No crack at solder joint. (2)No mechanical damage of appearance. | 1 | 0 |
| 8 | Static electricity immunity test | (1) Applied voltage $\pm 4\text{kV}$ (2) At rated input and load (3) Testing circuitry Fig.1 | (1)No protection circuit fail. (2)No output voltage drop due to control (3)No any other function fail. | 1 | 0 |

○Testing circuitry

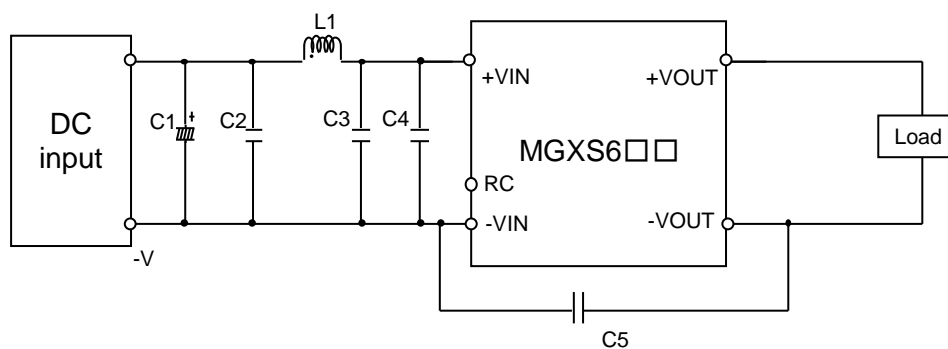


Fig.1 Testing circuitry

| | | |
|------|-----------|--|
| C1 : | MGXS624□□ | 100V 39 μ F Electric capacitor (LXVseries NIPPON CHEMI-CON) |
| C2 : | MGXS624□□ | 100V 2.2 μ F Ceramic capacitor (GRM31CR72A225K MURATA MANUFACTURING) |
| C3 : | MGXS624□□ | 100V 2.2 μ F Ceramic capacitor (GRM31CR72A225K MURATA MANUFACTURING) |
| C4 : | MGXS624□□ | 100V 2.2 μ F Ceramic capacitor (GRM31CR72A225K MURATA MANUFACTURING) |
| C5 : | MGXS624□□ | 2kV 2200pF Ceramic capacitor (GR443QR73D222K MURATA MANUFACTURING) |
| L1 : | MGXS624□□ | 1050mA 22 μ H Inductor(LQH5BPN220MT0 MURATA MANUFACTURING) |